

## PMP9595 REVB BOM

Designator	Quantity	Value	Description	Package	PartNumber	Mfr
C1, C21	2	470pF	CAP, CERM, 470pF, 50V, +/-5%, C0G/NP0, 0603	0603	C1608C0G1H471J	TDK
C2, C3, C4	3	180uF	CAP, OS-CON, 180uF, 25V, 4.65Arms, 0.016 ohm, E12	8x10	25SVPF180M	Sanyo
C5	1	DNP	CAP, DNP, E12	8x10		Sanyo
C6, C7	2	4.7uF	CAP, CERM, 4.7uF, 50V, +/-10%, X7R, 1210	1210	GRM32ER71H475KA88L	MuRata
C8, C20, C22	3	0.47uF	CAP, CERM, 0.47uF, 25V, +/-10%, X7R, 0603	0603	GRM188R71E474KA12D	MuRata
C9, C10, C11	3	10uF	CAP, CERM, 10uF, 25V, +/-20%, X7R, 1210	1210	C3225X7R1E106M	TDK
C12	1	1uF	CAP, CERM, 1uF, 25V, +/-10%, X7R, 0805	0805	C2012X7R1E105K	TDK
C13, C14, C23	3	1000pF	CAP, CERM, 1000pF, 50V, +/-10%, X7R, 0603	0603	GRM188R71H102KA01D	MuRata
C15, C24	2	3.3uF	CAP, CERM, 3.3uF, 50V, +/-10%, X7R, 1206	1206	C3216X7R1H335K160AC	TDK
C16	1	100pF	CAP, CERM, 100pF, 50V, +/-5%, C0G/NP0, 0603	0603	C1608C0G1H101J	TDK
C17	1	0.015uF	CAP, CERM, 0.015uF, 50V, +/-10%, X7R, 0603	0603	C1608X7R1H153K	TDK
C18, C25	2	10uF	CAP, CERM, 10uF, 25V, +/-10%, X7R, 1206	1206	C3216X7R1E106K	TDK
C19	1	0.1uF	CAP, CERM, 0.1uF, 50V, +/-10%, X7R, 0603	0603	C1608X7R1H104K	TDK
C26, C27	2	DNP	CAP, DNP	0603		
D1, D2	2	PMEG6010CEH	Diode, Schottky, 60V, 1A, SOD-123F	SOD-123F	PMEG6010CEH	NXP
J1, J3	2		TERMINAL BLOCK, 15A, VERT 2POS, TH	5.08mm	ED120/2DS	On-Shore Tech
J2, J4	2	PEC03SAAN	Header, Male 3-pin, 100mil spacing,	0.100 inch x 3	PEC03SAAN	Sullins
L1, L2	2	2.2uH	Inductor, Shielded, Composite, 2.2uH, 32A, 0.00255 ohm, SMD	Inductor, 11.3x10x10mm	XAL1010-222MEB	Coilcraft
Q1, Q3, Q5, Q7	4	DNP	MOSFET, TO-252, DNP	DPAK		
Q2, Q4, Q6, Q8	4	CSD18532Q5B	MOSFET, N-CH, 60V, 172A, SON 5x6mm	SON 5x6mm	CSD18532Q5B	TI
R1, R14	2	7.5	RES, 7.5 ohm, 5%, 1W, 2010	2010	CRM2010-JW-7R5ELF	Bourns
R2, R15	2	0.002	RES, 0.002 ohm, 1%, 2W, 2512	2512	CSNL2512FT2L00	Stackpole
R3, R4, R16, R17	4	100	RES, 0 ohm, 5%, 0.1W, 0603	0603	ERJ-3GEY0R00V	Panasonic
R5, R9	2	49.9k	RES, 49.9k ohm, 1%, 0.1W, 0603	0603	CRCW060349K9FKEA	Vishay-Dale
R6, R18	2	3.3	RES, 3.3 ohm, 5%, 0.1W, 0603	0603	CRCW06033R30JNEA	Vishay-Dale
R7	1	12.4k	RES, 12.4k ohm, 1%, 0.1W, 0603	0603	CRCW060312K4FKEA	Vishay-Dale
R10	1	100	RES, 100 ohm, 1%, 0.1W, 0603	0603	CRCW0603100RFKEA	Vishay-Dale
R8, R11, R19	3	21.5k	RES, 21.5k ohm, 1%, 0.1W, 0603	0603	CRCW060321K5FKEA	Vishay-Dale
R12	1	27.4k	RES, 27.4k ohm, 1%, 0.1W, 0603	0603	CRCW060327K4FKEA	Vishay-Dale
R13	1	3.57k	RES, 3.57k ohm, 1%, 0.1W, 0603	0603	CRCW06033K57FKEA	Vishay-Dale
R20, R21	2	DNP	RES, DNP	0603		
TP1, TP2, TP3, TP6, TP9	5	Red	Test Point, Multipurpose, Red, TH	Keystone5010	5010	Keystone
TP4, TP5, TP7, TP8, TP10	5	Black	Test Point, Multipurpose, Black, TH	Keystone5011	5011	Keystone
U1, U2	2	LM5122	Wide Input Synchronous Boost Controller with Multiple Phase Capability, PWP0020A	PWP0020A	LM5122MH/NOPB	TI

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